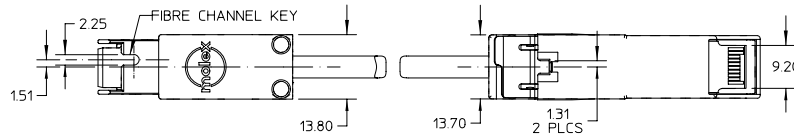
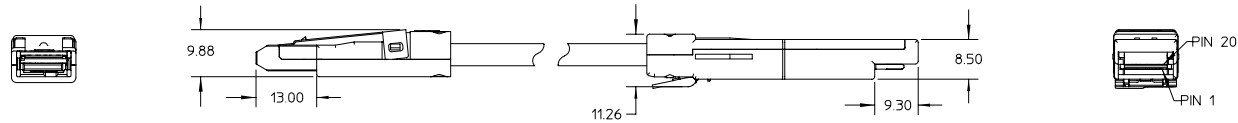
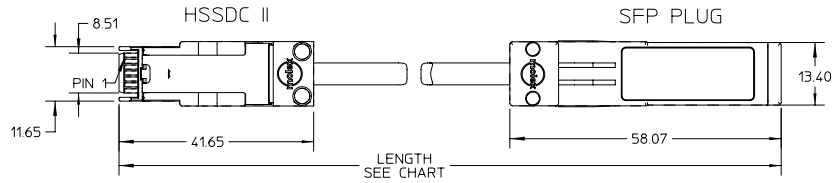


WIRING DIAGRAM					
SFP			HSSDC II		
PIN	SIGNAL	PIN	SIGNAL	PIN	SIGNAL
19	Tx-	2	Rx-		
18	Tx+	3	Rx+		
13	Rx+	5	Tx+		
12	Rx-	6	Tx-		



SFP NOTES:

- MATERIALS  
 BACKSHELLS - NICKEL PLATED ZINC  
 LATCH - GLASS FILLED POLYCARBONATE  
 PCB - FR-4  
 RIVETS - TIN PLATED STEEL
- IMPEDANCE MATCHING SFP (100 OHMS) TO HSSDC II (150 OHMS)

HSSDC II NOTES:

- MATERIALS  
 BACKSHELLS - NICKEL PLATED ZINC  
 LATCH - TIN PLATED PHOS BRONZE  
 PCB - FR-4  
 RIVETS - TIN PLATED STEEL
- CHARACTERISTIC IMPEDANCE 150 OHMS DIFFERENTIAL

CABLE NOTES:

- CHARACTERISTIC IMPEDANCE 150 ± 10 OHMS MEASURED DIFFERENTIAL
- SEE MOLEX DRAWINGS SD-71153-7\*\*\* FOR FURTHER CABLE DETAILS

PART NUMBER	LENGTH
73929-4001	1 M ± 0.05 M
73929-4002	3 M ± 0.07 M
73929-4003	5 M ± 0.08 M
73929-4005	2 M ± 0.06 M
73929-4006	4 M ± 0.07 M

EC NO: UDDIT 2002020803 DRAWN: DSLEWIS 2002/03/08 CHK: DDOYE 2002/02/12 APPR: DDOYE 2002/02/08/14	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY	
	DESCRIPTION -0 0	4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± 0.3 ± ---	DIMENSION STYLE MM ONLY	TITLE			
		ANGULAR ± 2 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SFP TO HSSDC II PATCH CABLE ASSEMBLY FIBRE CHANNEL 150 OHMS			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MOLEX INCORPORATED				
REV	DESCRIPTION	APPROVED BY DATE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
A		DLD 2001/12/06	739294002	SD-73929-400	1 OF 1	B	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							